

---

# HD74ALVC162835

## 18-bit Universal Bus Driver with 3-state Outputs

REJ03D0055-0700Z  
(Previous ADE-205-201E (Z) )  
Rev.7.00  
Oct.02.2003

---

### Description

The HD74ALVC162835 is an 18-bit universal bus driver designed for 2.3 V to 3.6 V  $V_{CC}$  operation.

Data flow from A to Y is controlled by the output enable ( $\overline{OE}$ ). The device operates in the transparent mode when the latch enable (LE) is high. When LE is low, the A data is latched if the clock (CLK) input is held at a high or low logic level. If the LE is low, the A data is stored in the latch/flip flop on the low to high transition of CLK. When  $\overline{OE}$  is high, the outputs are in the high impedance state.

To ensure the high impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup register; the minimum value of the register is determined by the current sinking capability of the driver.

All outputs, which are designed to sink up to 12 mA, include 26  $\Omega$  resistors to reduce overshoot and undershoot.

### Features

- Meets “PC SDRAM registered DIMM design support document, Rev. 1.2”
- $V_{CC} = 2.3 \text{ V to } 3.6 \text{ V}$
- Typical  $V_{OL}$  ground bounce  $< 0.8 \text{ V}$  (@  $V_{CC} = 3.3 \text{ V}$ ,  $T_a = 25^\circ\text{C}$ )
- Typical  $V_{OH}$  undershoot  $> 2.0 \text{ V}$  (@  $V_{CC} = 3.3 \text{ V}$ ,  $T_a = 25^\circ\text{C}$ )
- High output current  $\pm 12 \text{ mA}$  (@  $V_{CC} = 3.0 \text{ V}$ )
- All outputs have equivalent 26  $\Omega$  series resistors, so no external resistors are required

**Function Table**

Inputs				Output Y
$\overline{OE}$	LE	CLK	A	
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	↑	L	L
L	L	↑	H	H
L	L	L or H	X	$Y_0^{*1}$

H : High level

L : Low level

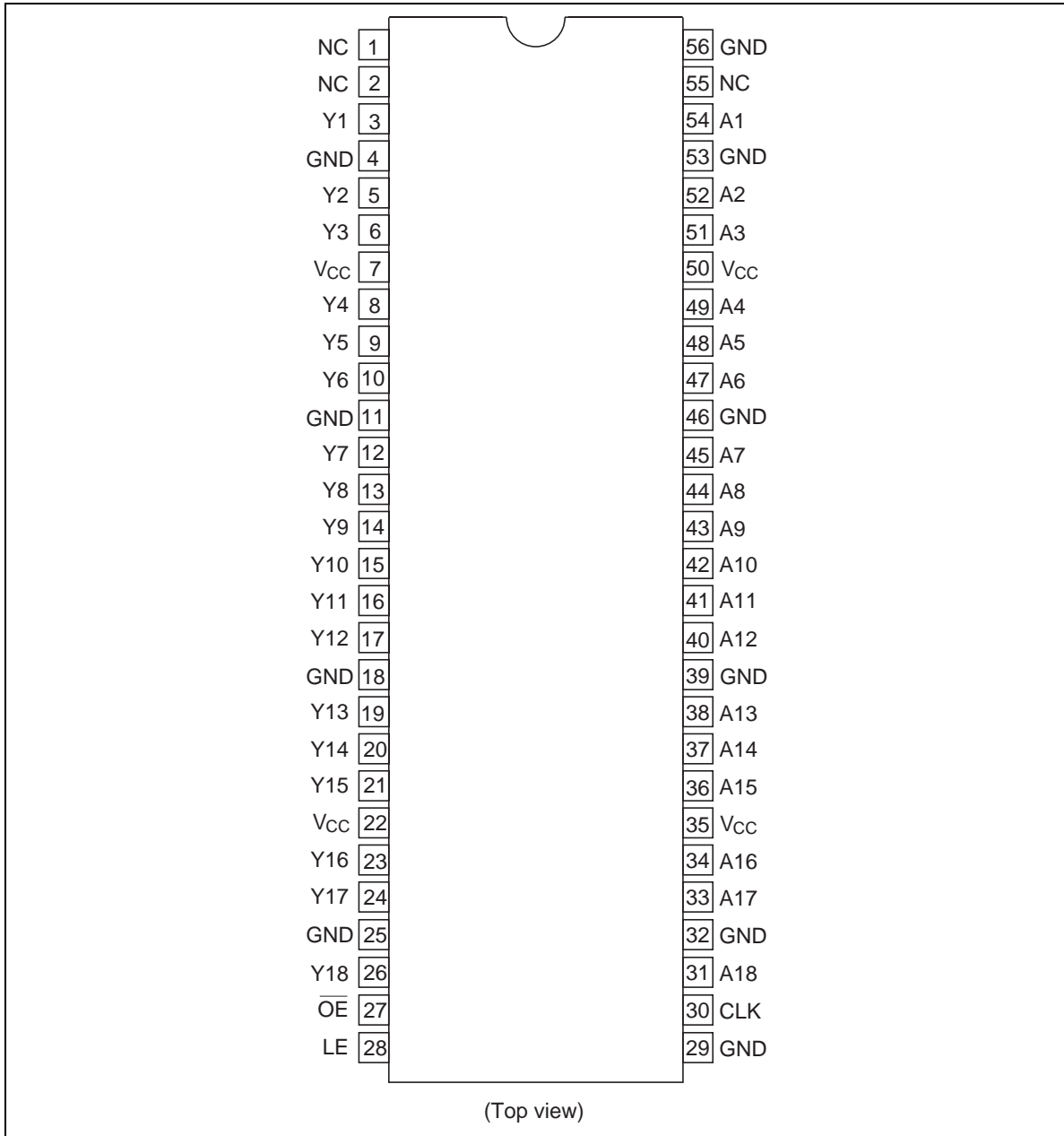
X : Immaterial

Z : High impedance

↑ : Low to high transition

Note: 1. Output level before the indicated steady-state input conditions were established.

Pin Arrangement



### Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	$V_{CC}$	-0.5 to 4.6	V	
Input voltage range <sup>*1</sup>	$V_I$	-0.5 to 4.6	V	
Output voltage range <sup>*1, 2</sup>	$V_O$	-0.5 to $V_{CC}+0.5$	V	
Input clamp current	$I_{IK}$	-50	mA	$V_I < 0$
Output clamp current	$I_{OK}$	$\pm 50$	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	$I_O$	$\pm 50$	mA	$V_O = 0$ to $V_{CC}$
$V_{CC}$ , GND current / pin	$I_{CC}$ or $I_{GND}$	$\pm 100$	mA	
Maximum power dissipation at $T_a = 55^\circ\text{C}$ (in still air) <sup>*3</sup>	$P_T$	1	W	TSSOP
Storage temperature range	$T_{stg}$	-65 to 150	$^\circ\text{C}$	

Notes: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating condition" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

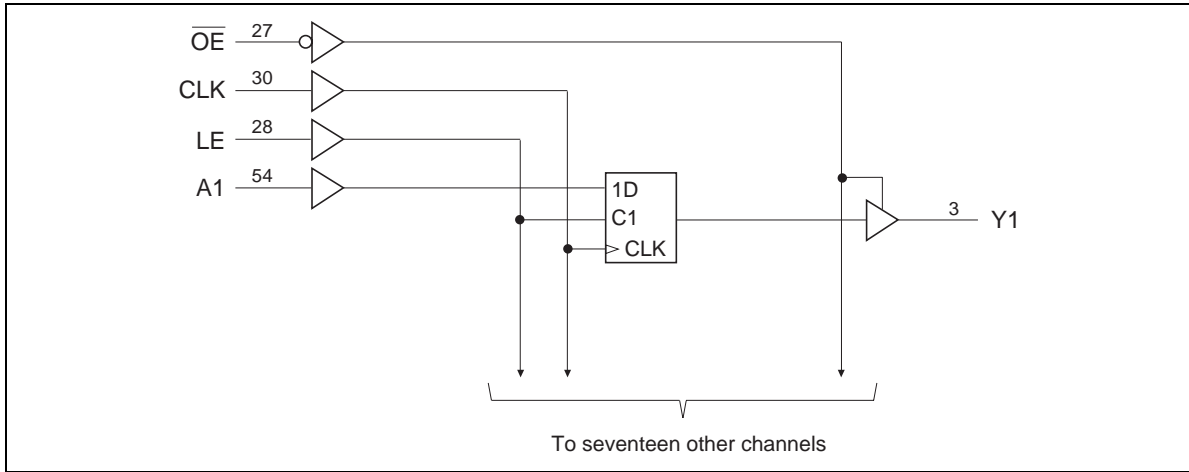
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp current ratings are observed.
2. The input and output positive-voltage ratings may be exceeded up to 4.6 V if the input and output clamp-current ratings are observed.
3. The maximum power dissipation is calculated using a junction temperature of 150 $^\circ\text{C}$  and board trace length of 750 mils.

### Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage	$V_{CC}$	2.3	3.6	V	
Input voltage	$V_I$	0	$V_{CC}$	V	
Output voltage	$V_O$	0	$V_{CC}$	V	
High-level output current	$I_{OH}$	—	-6	mA	$V_{CC} = 2.3\text{ V}$
		—	-8		$V_{CC} = 2.7\text{ V}$
		—	-12		$V_{CC} = 3.0\text{ V}$
Low-level output current	$I_{OL}$	—	6	mA	$V_{CC} = 2.3\text{ V}$
		—	8		$V_{CC} = 2.7\text{ V}$
		—	12		$V_{CC} = 3.0\text{ V}$
Input transition rise or fall rate	$\Delta t/\Delta v$	0	10	ns/V	
Operating free-air temperature	$T_a$	-40	85	$^\circ\text{C}$	

Note: Unused or floating control pins must be held high or low.

**Logic Diagram**



**Electrical Characteristics**

Item	Symbol	V <sub>CC</sub> (V)	Ta = -40 to 85°C		Unit	Test Conditions
			Min	Max		
Input voltage	V <sub>IH</sub>	2.3 to 2.7	1.7	—	V	
		2.7 to 3.6	2.0	—		
	V <sub>IL</sub>	2.3 to 2.7	—	0.7	V	
		2.7 to 3.6	—	0.8		
Output voltage	V <sub>OH</sub>	2.3 to 3.6	V <sub>CC</sub> -0.2	—	V	I <sub>OH</sub> = -100 μA
		2.3	1.9	—		I <sub>OH</sub> = -4 mA, V <sub>IH</sub> = 1.7 V
		2.3	1.7	—		I <sub>OH</sub> = -6 mA, V <sub>IH</sub> = 1.7 V
		3.0	2.4	—		I <sub>OH</sub> = -6 mA, V <sub>IH</sub> = 2.0 V
		2.7	2.0	—		I <sub>OH</sub> = -8 mA, V <sub>IH</sub> = 2.0 V
		3.0	2.0	—		I <sub>OH</sub> = -12 mA, V <sub>IH</sub> = 2.0 V
	V <sub>OL</sub>	2.3 to 3.6	—	0.2	V	I <sub>OL</sub> = 100 μA
		2.3	—	0.4		I <sub>OL</sub> = 4 mA, V <sub>IL</sub> = 0.7 V
		2.3	—	0.55		I <sub>OL</sub> = 6 mA, V <sub>IL</sub> = 0.7 V
		3.0	—	0.55		I <sub>OL</sub> = 6 mA, V <sub>IL</sub> = 0.8 V
		2.7	—	0.6		I <sub>OL</sub> = 8 mA, V <sub>IL</sub> = 0.8 V
		3.0	—	0.8		I <sub>OL</sub> = 12 mA, V <sub>IL</sub> = 0.8 V
Input current	I <sub>IN</sub>	3.6	—	±5.0	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND
Off state output current	I <sub>OZ</sub>	3.6	—	±10	μA	V <sub>OUT</sub> = V <sub>CC</sub> or GND
Quiescent supply current	I <sub>CC</sub>	3.6	—	40	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND
	ΔI <sub>CC</sub>	3.0 to 3.6	—	750	μA	One input at (V <sub>CC</sub> -0.6)V, other inputs at V <sub>CC</sub> or GND

**Switching Characteristics**

(Ta = -40 to 85°C)

Item	Symbol	V <sub>CC</sub> (V)	Min	Typ	Max	Unit	From (Input)	To (Output)		
Maximum clock frequency	f <sub>max</sub>	2.5±0.2	150	—	—	MHz				
		2.7	150	—	—					
		3.3±0.3	150	—	—					
Propagation delay time	t <sub>PLH</sub>	2.5±0.2	1.0	—	5.0	ns	A	Y		
		2.7	—	—	5.0					
		3.3±0.3	1.0	—	4.2					
	t <sub>PHL</sub>	2.5±0.2	1.3	—	5.9		LE	Y		
		2.7	—	—	5.8					
		3.3±0.3	1.3	—	5.1					
		2.5±0.2	1.4	—	6.3				CLK	Y
		2.7	—	—	6.1					
		3.3±0.3	1.4	—	5.4					
Output enable time	t <sub>ZH</sub>	2.5±0.2	1.4	—	6.3	ns	OE	Y		
		2.7	—	—	6.5					
		3.3±0.3	1.1	—	5.5					
Output disable time	t <sub>HZ</sub>	2.5±0.2	1.0	—	4.7	ns	OE	Y		
		2.7	—	—	4.9					
		3.3±0.3	1.3	—	4.5					
Input capacitance	C <sub>IN</sub>	3.3	3.0	4.5	7.0	pF	Control inputs			
		3.3	3.0	6.0	9.0		Data inputs			
Output capacitance	C <sub>O</sub>	3.3	3.0	7.0	9.0	pF	Y ports			

Switching Characteristics (cont.)

(T<sub>a</sub> = -40 to 85°C)

Item	Symbol	V <sub>CC</sub> (V)	Min	Typ	Max	Unit	From (Input)
Setup time	t <sub>su</sub>	2.5±0.2	2.2	—	—	ns	Data before CLK↑
		2.7	2.1	—	—		
		3.3±0.3	1.7	—	—		
		2.5±0.2	1.9	—	—		Data before $\overline{LE}$ ↑ CLK "H"
		2.7	1.6	—	—		
		3.3±0.3	1.5	—	—		
		2.5±0.2	1.3	—	—		Data before $\overline{LE}$ ↑ CLK "L"
		2.7	1.1	—	—		
		3.3±0.3	1.0	—	—		
Hold time	t <sub>h</sub>	2.5±0.2	0.6	—	—	ns	Data after CLK↑
		2.7	0.6	—	—		
		3.3±0.3	0.7	—	—		
		2.5±0.2	1.4	—	—		Data after $\overline{LE}$ ↑ CLK "H" or "L"
		2.7	1.7	—	—		
		3.3±0.3	1.4	—	—		
Pulse width	t <sub>w</sub>	2.5±0.2	3.3	—	—	ns	$\overline{LE}$ "L"
		2.7	3.3	—	—		
		3.3±0.3	3.3	—	—		
		2.5±0.2	3.3	—	—		CLK "H" or "L"
		2.7	3.3	—	—		
		3.3±0.3	3.3	—	—		

**Switching Characteristics (cont.)**

(Ta = 0 to 85°C)

Item	Symbol	V <sub>CC</sub> (V)	Min	Typ	Max	Unit	FROM (Input)	TO (Output)
Propagation delay time	C <sub>L</sub> =0pF <sup>*1</sup>	3.3±0.165	0.9	—	2.0	ns	A	Y
	C <sub>L</sub> =50pF		1.0	—	4.5			
	C <sub>L</sub> =0pF <sup>*1</sup>	3.3±0.165	1.4	—	2.9	CLK	Y	
	C <sub>L</sub> =50pF		1.9	—	4.5			
	C <sub>L</sub> =50pF	t <sub>SSO</sub> <sup>*1,2</sup>	3.3±0.165	1.9	—	4.8	CLK, A	Y
Output rise / fall time	C <sub>L</sub> =50pF	t <sub>TLH</sub> , t <sub>THL</sub> <sup>*1</sup>	3.3±0.165	1.0	—	2.5	volts/ ns	Y

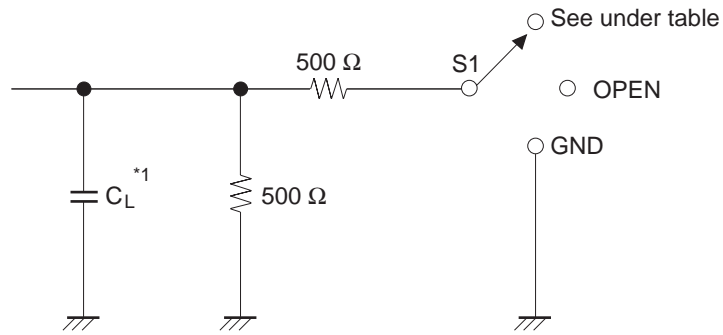
- Notes: 1. This parameter is characterized but not tested.  
 2. t<sub>SSO</sub> : Simultaneous switching output time.

**Operating Characteristics**

(Ta = 25 °C)

Item	Symbol	V <sub>CC</sub> = 2.5±0.2 V	V <sub>CC</sub> = 3.3±0.3 V	Unit	Test Conditions	
		Typ	Typ			
Power dissipation capacitance	Outputs enable	C <sub>pd</sub>	22.0	24.5	pF	C <sub>L</sub> = 0, f = 10 MHz
	Outputs disable		5.0	6.0		

Test Circuit

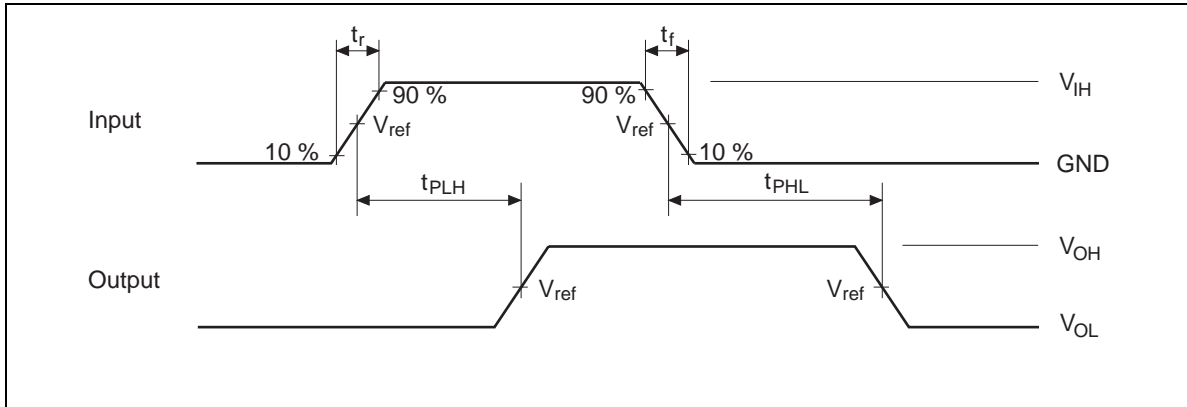


Load Circuit for Outputs

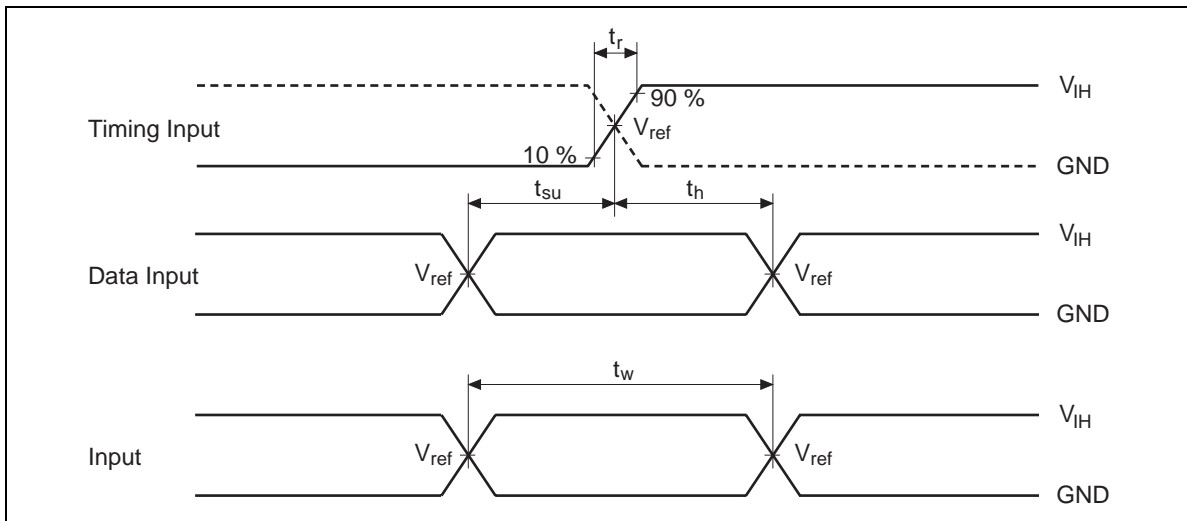
Symbol	V <sub>CC</sub> =2.5±0.2V	V <sub>CC</sub> =2.7V, 3.3±0.3V
t <sub>PLH</sub> /t <sub>PHL</sub>	OPEN	OPEN
t <sub>su</sub> /t <sub>h</sub> /t <sub>w</sub>	OPEN	OPEN
t <sub>ZH</sub> /t <sub>HZ</sub>	GND	GND
t <sub>ZL</sub> /t <sub>LZ</sub>	2 × V <sub>CC</sub>	6.0 V
C <sub>L</sub>	30 pF	50 pF

Note: 1. C<sub>L</sub> includes probe and jig capacitance.

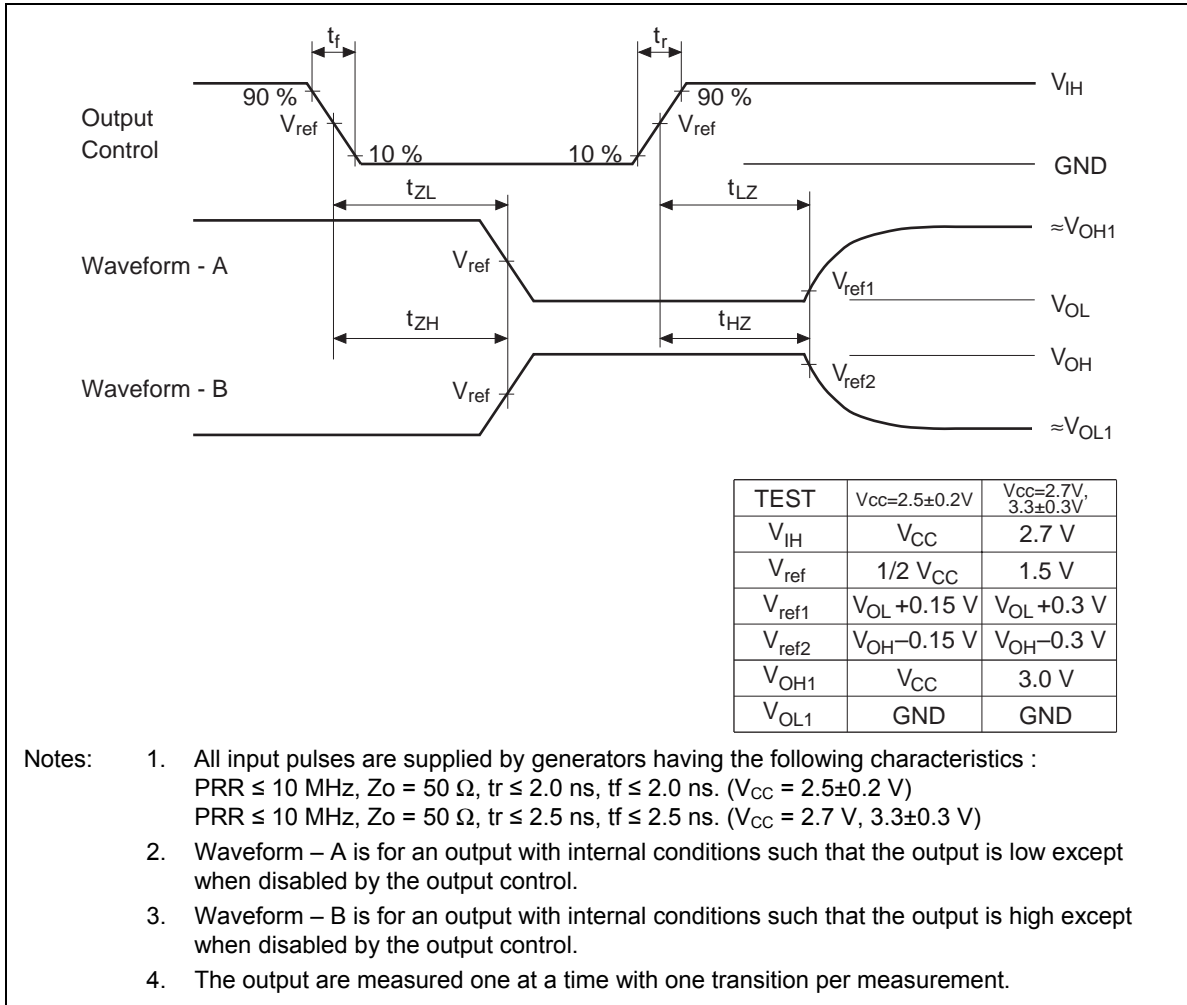
Waveforms - 1



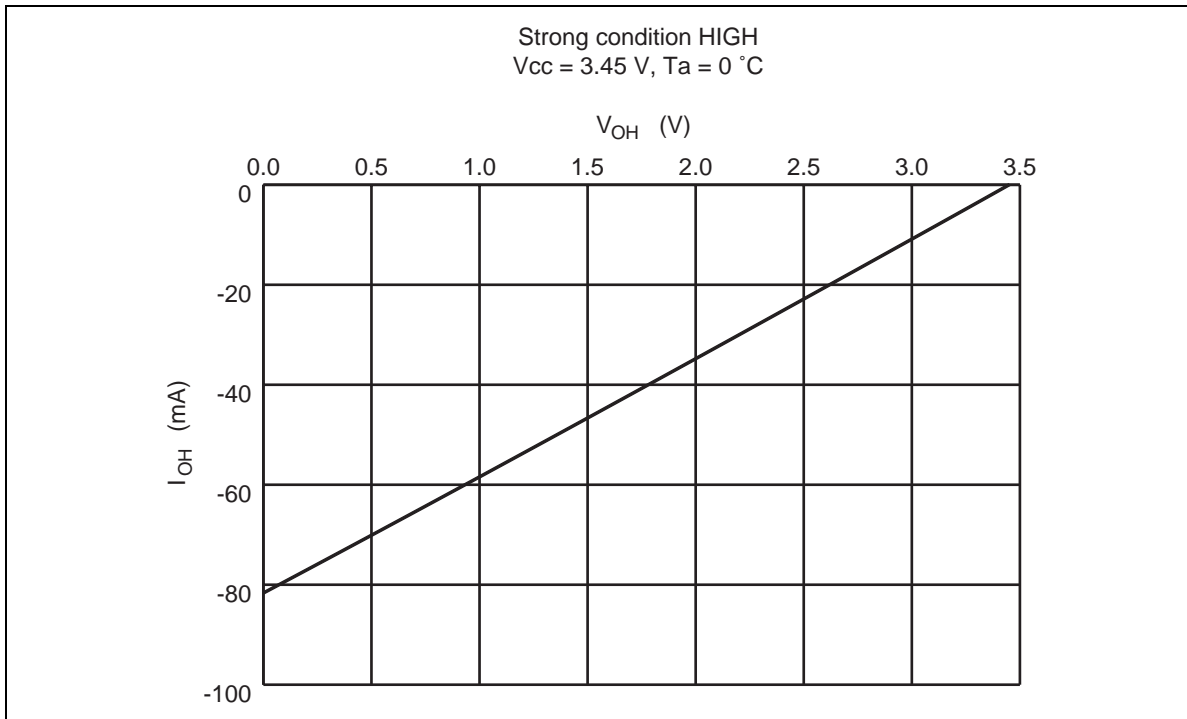
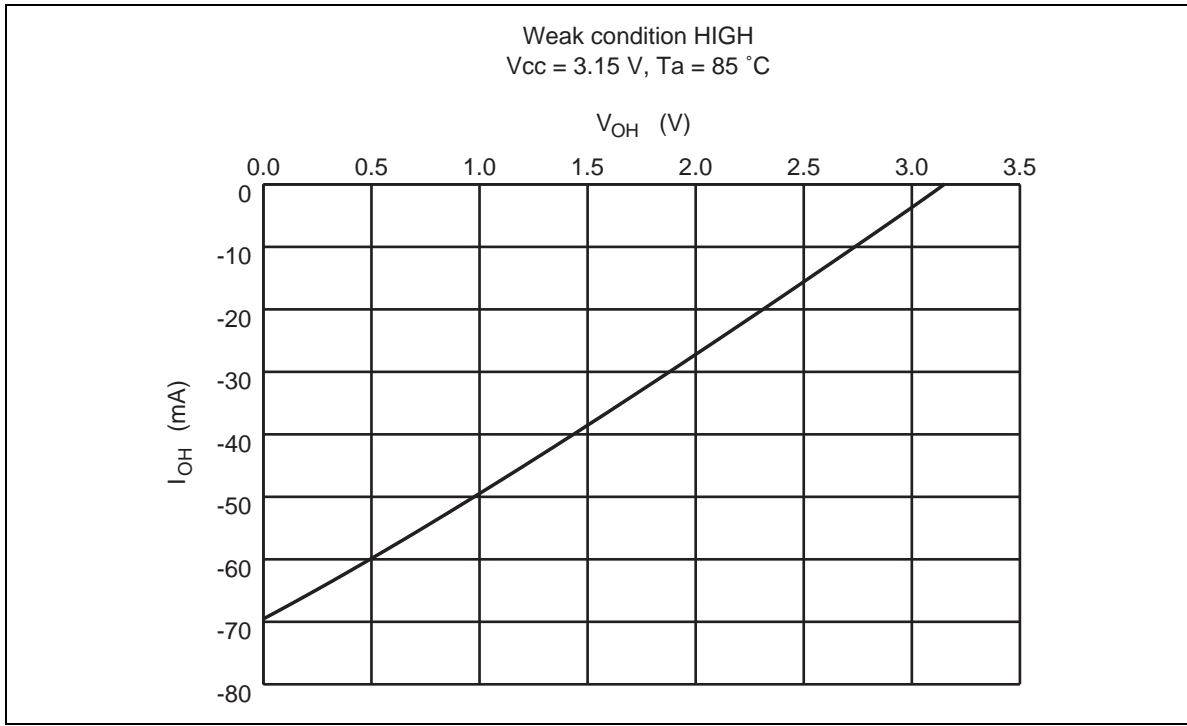
Wave forms - 2

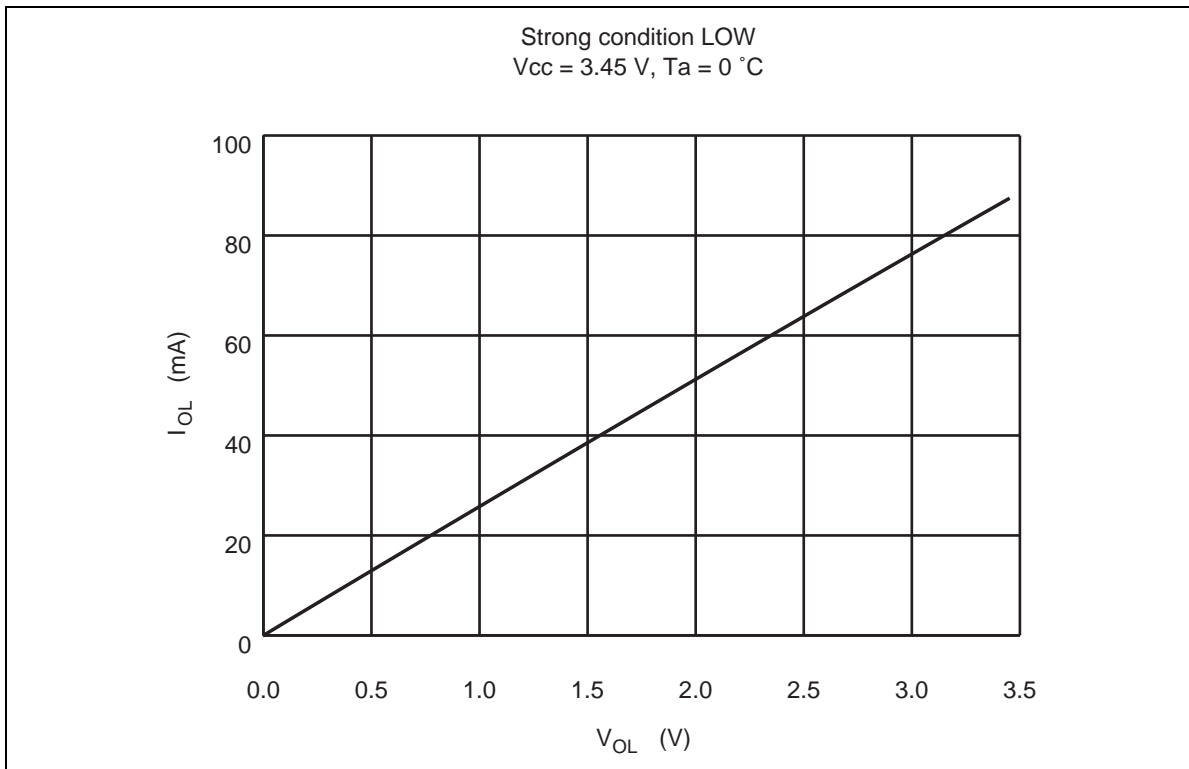
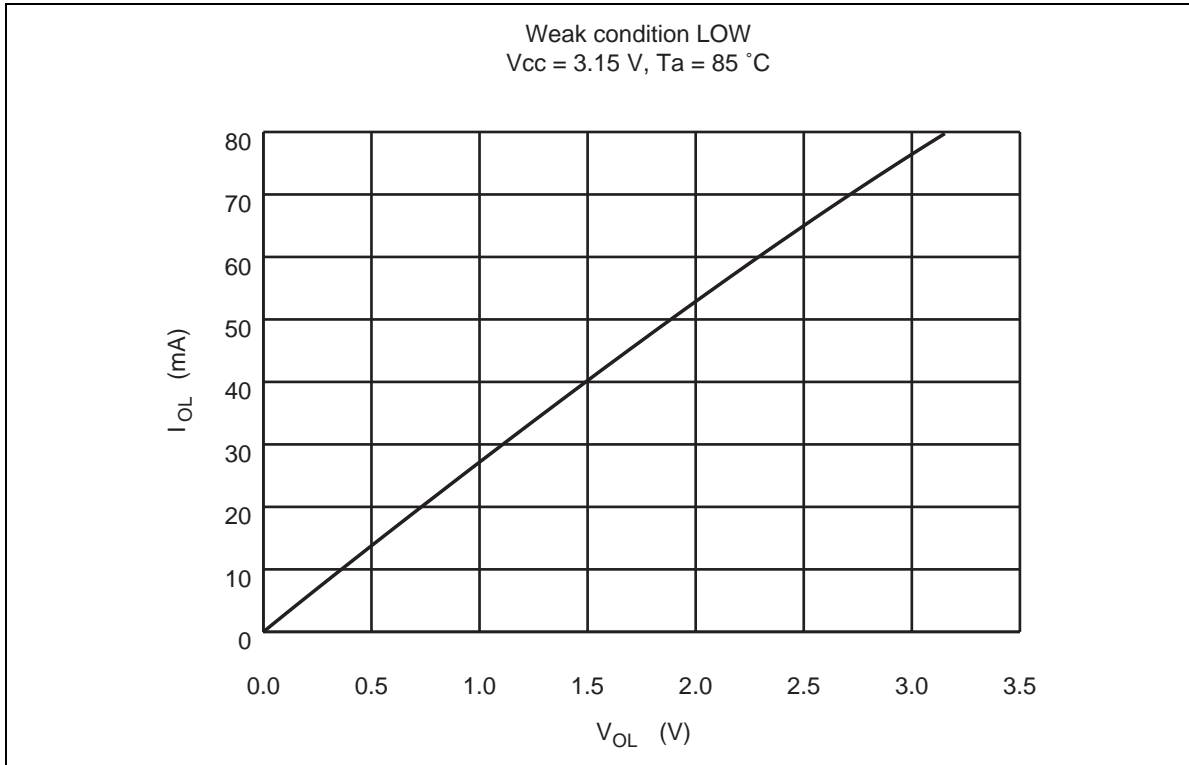


Wave forms – 3

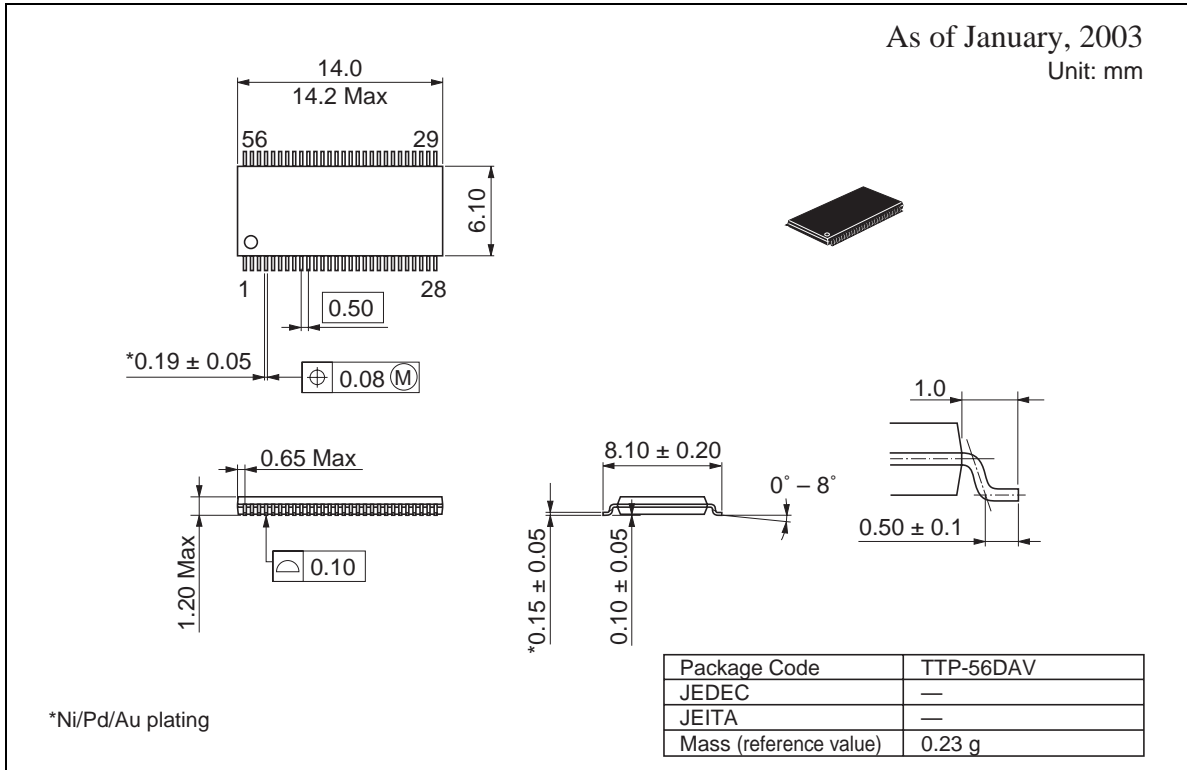


IV Characteristics for Register Output (Measured value)





Package Dimensions



## RENESAS Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

---

Keep safety first in your circuit designs!

1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.  
Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
  2. Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
  3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.  
The information described here may contain technical inaccuracies or typographical errors.  
Renesas Technology Corp. assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.  
Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (<http://www.renesas.com>).
  4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
  5. Renesas Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
  6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials.
  7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.  
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
  8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.
- 



### RENESAS SALES OFFICES

<http://www.renesas.com>

**Renesas Technology America, Inc.**  
450 Holger Way, San Jose, CA 95134-1368, U.S.A  
Tel: <1> (408) 382-7500 Fax: <1> (408) 382-7501

**Renesas Technology Europe Limited.**  
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom  
Tel: <44> (1628) 585 100, Fax: <44> (1628) 585 900

**Renesas Technology Europe GmbH**  
Dornacher Str. 3, D-85622 Feldkirchen, Germany  
Tel: <49> (89) 380 70 0, Fax: <49> (89) 929 30 11

**Renesas Technology Hong Kong Ltd.**  
7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Hong Kong  
Tel: <852> 2265-6688, Fax: <852> 2375-6836

**Renesas Technology Taiwan Co., Ltd.**  
FL 10, #99, Fu-Hsing N. Rd., Taipei, Taiwan  
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

**Renesas Technology (Shanghai) Co., Ltd.**  
26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China  
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

**Renesas Technology Singapore Pte. Ltd.**  
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632  
Tel: <65> 6213-0200, Fax: <65> 6278-8001